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Attorney Docket No. 408204

IN THE SPECIFICATION

In accordance with 37 C.F.R. § 1.121(b)(1), Applicants amend the specification as follows:

Please amend paragraph 45 as follows:

FIG. 9 shows exemplary process 90 for manufacture of a solder bar, such as solder bar 70 (FIG. 7). A chip is prepared 91 for incorporation into a package having electrical contact pads operable to receive a conductive adhesion layer. An adhesion layer, e.g., aluminum, is applied 92 to the pad of the chip. The adhesion layer application 92 may entail screen printing or other methods of application and may include the application of nickel, vanadium, copper, titanium, tungsten, or aluminum. A passivation layer, e.g., polyimide, silicon nitride, silicon oxide, polysilicon, or oxinitride, is applied 93, for example, by chemical vapor deposition and covers the chip and adhesion layers. A UBM layer, e.g., aluminum, nickel-vanadium, copper, titanium, tungsten, vanadium, tin, gold, silver, lead or titanium-tungsten, is applied 94 substantially to the adhesion layer. The UBM layer may be applied 94 by etching, photolithography, sputtering, or other method of application. A BCB layer is applied 95 through a mask, thus preventing application to areas where the passivation layer is to be removed, such as areas covering the adhesion layers. Voids are created 96 by exposing the chip to lithography which softens the areas of the passivation layer not protected by the BCB layer. The softened passivation layer is washed away exposing the adhesion layer. As a matter of design choice, a base metal, such as copper, is electroplated 97 onto the UBM layer. A solder layer is then electroplated 98 onto the base metal, if provided, or if the base metal is omitted, electroplated 98 directly to the UBM layer. It will be appreciated that one or more of the deposition steps may be eliminated, for example, where passivation is not required or elimination of the UBM if the base metal or solder is capable of bonding directly to the adhesion layer.